

ON Semiconductor®

FDB9406-F085

N-Channel PowerTrench® MOSFET **40 V, 110 A, 1.8 m**Ω

Features

- Typ R_{DS(on)} = 1.31m Ω at V_{GS} = 10V, I_D = 80A
- Typ $Q_{g(tot)}$ = 107nC at V_{GS} = 10V, I_D = 80A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter/Alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems





TO-263

FDB SERIES

MOSFET Maximum Ratings $T_J = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter		Ratings	Units	
V_{DSS}	Drain to Source Voltage		40	V	
V_{GS}	Gate to Source Voltage		±20	V	
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	110	А	
E _{AS}	Pulsed Drain Current	T _C = 25°C	See Figure4	7 ^	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	174	mJ	
D	Power Dissipation		176	W	
P_{D}	Derate above 25°C		1.18	W/°C	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.85	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB9406	FDB9406-F085	D2-PAK(TO-263)	330mm	24mm	800 units

- Current is limited by bondwire configuration.
 Starting T_J = 25°C, L = 0.045mH, I_{AS} = 88A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.
- 3: $R_{\theta,JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder

mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max.

Electrical Characterist	ICS $T_J = 25^{\circ}$ C unless otherwise noted
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Parameter

Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	I _D = 250μA, V	_{GS} = 0V	40	-	-	V
	Drain-to-Source Leakage Current	V _{DS} =40V,	$T_J = 25^{\circ}C$	-	-	1	μА
DSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate-to-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0	2.83	4.0	V
Р	R _{DS(an)} Drain-to-Source On Resistance L	I _D = 80A,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	1.31	1.8	mΩ
CDS(on)		V _{GS} = 10V	$T_J = 175^{\circ}C(Note 4)$	-	2.2	2.8	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	\/ - 25\/ \/ -	0) /	-	7710	-	pF
C _{oss}	Output Capacitance	V _{DS} = 25V, V _{GS} = 0V, — f = 1MHz		-	2015	-	pF
C _{rss}	Reverse Transfer Capacitance			-	140	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.7	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	V _{DD} = 32V	-	107	138	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I _D = 80A	-	14	19	nC
Q_{gs}	Gate-to-Source Gate Charge			-	33	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	18	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	160	ns
t _{d(on)}	Turn-On Delay		-	32	-	ns
t _r	Rise Time	V _{DD} = 20V, I _D = 80A,	-	81	-	ns
t _{d(off)}	Turn-Off Delay	$V_{GS} = 10V, R_{GEN} = 6\Omega$	-	50	-	ns
t _f	Fall Time		-	23	-	ns
t_{off}	Turn-Off Time	1	-	-	93	ns

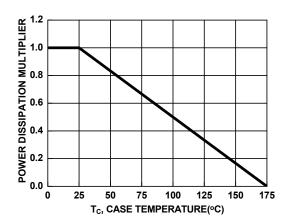
Drain-Source Diode Characteristics

V_{SD}	Source-to-Drain Diode Voltage	I _{SD} = 80A, V _{GS} = 0V	-	-	1.25	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	85	110	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =32V	-	122	160	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



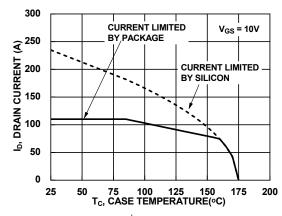
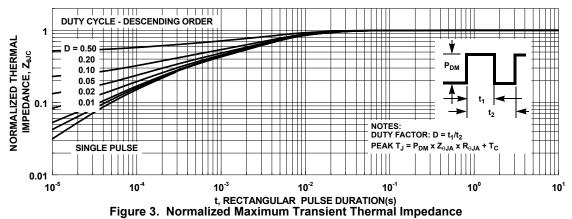


Figure 1. Normalized Power Dissipation vs. Case **Temperature**

Figure 2. Maximum Continuous Drain Current vs. Case Temperature



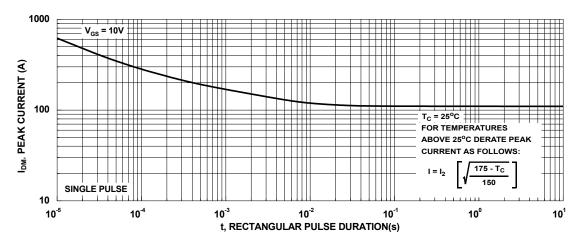


Figure 4. Peak Current Capability

Typical Characteristics

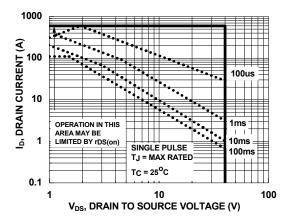
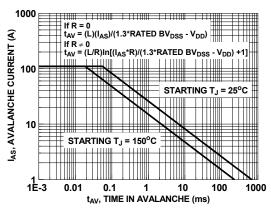


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

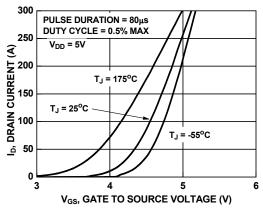


Figure 7. Transfer Characteristics

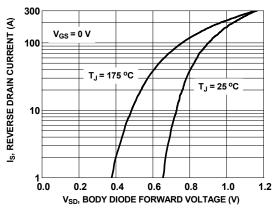


Figure 8. Forward Diode Characteristics

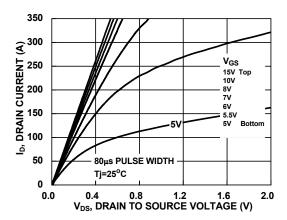


Figure 9. Saturation Characteristics

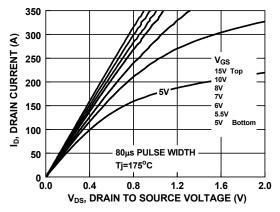


Figure 10. Saturation Characteristics

Typical Characteristics

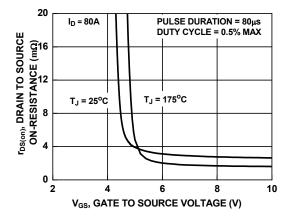


Figure 11. R_{DSON} vs. Gate Voltage

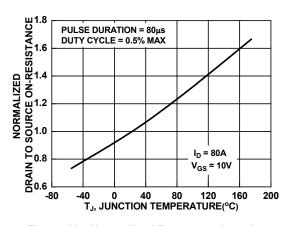


Figure 12. Normalized R_{DSON} vs. Junction Temperature

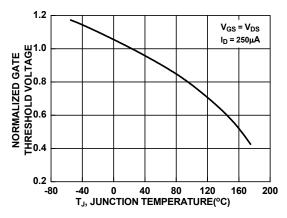


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

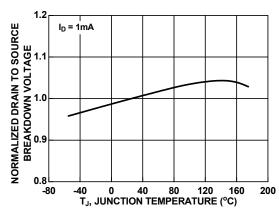


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

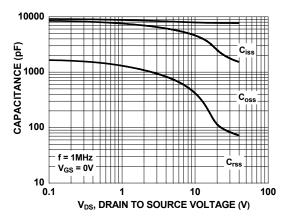


Figure 15. Capacitance vs. Drain to Source Voltage

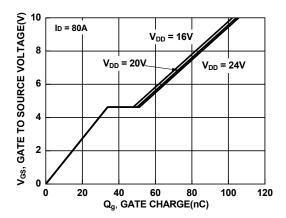


Figure 16. Gate Charge vs. Gate to Source Voltage

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